

| Name of the part | Pb | Cd | Hg | Cr-VI | PBB | PBDE |
|------------------|----|----|----|-------|-----|------|
| Die              | X  | 0  | 0  | 0     | 0   | 0    |
| Lead Frame       | 0  | 0  | 0  | 0     | 0   | 0    |
| Mould Compound   | 0  | 0  | 0  | 0     | 0   | 0    |
| Post-plating     | 0  | 0  | 0  | 0     | 0   | 0    |
| Solder Wire      | X  | 0  | 0  | 0     | 0   | 0    |
| Wire             | 0  | 0  | 0  | 0     | 0   | 0    |

0: Indicates all homogeneous materials` hazardous substances content are below the SJ/T11363-2006 limit.

X: Indicates that the hazardous substance content contained in any one of the homogenous materials of the part exceeded the MCV limits specified in the Standard SJ/T 11363-2006.

Remark: All WeEn Semiconductors products have an environmental friendly use period (EFUP) of 50 years.

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